



Material Content Data Sheet



Halogen-Free

Sales Product Name	2ED2108S06F	Issued	14. May 2021
MA#	MA002704372		
Package	PG-DSO-8-70	Weight*	75.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.437	1.91	1.91	19101	19101
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.031	0.04		418	
	non noble metal	iron	7439-89-6	0.628	0.84		8351	
	non noble metal	copper	7440-50-8	25.502	33.91	34.80	339093	347966
wires	noble metal	palladium	7440-05-3	0.000			6	
	non noble metal	copper	7440-50-8	0.045	0.06	0.06	604	610
encapsulation	organic material	carbon black	1333-86-4	0.230	0.31		3052	
	plastics	epoxy resin	-	6.198	8.24		82417	
	inorganic material	silicondioxide	60676-86-0	39.486	52.49	61.04	525023	610492
leadfinish	non noble metal	tin	7440-31-5	0.833	1.11	1.11	11081	11081
plating	noble metal	silver	7440-22-4	0.134	0.18	0.18	1776	1776
glue	plastics	acrylic resin	-	0.148	0.20		1974	
	noble metal	silver	7440-22-4	0.526	0.70	0.90	7000	8974
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com